



Product Change Notification

CN-202302012F

Issue date: 13 Oct 2023

Effective date: 25 Jan 2024

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Transfer of wafer back grinding process to Nexperia ATGD for SOT1176 products

Change Category

| | | | | | |
|--------------------------|--------------------------|--------------------------|--------------------------|--------------------------|--------------------------|
| <input type="checkbox"/> |
| Wafer | Assembl | | | Test | Design |
| Fab | y | | | Location | |
| Process | Process | <input type="checkbox"/> | Product Marking | | <input type="checkbox"/> |
| <input type="checkbox"/> | <input type="checkbox"/> | <input type="checkbox"/> | Mechanical | <input type="checkbox"/> | Test |
| Wafer | Assembl | | Specification | <input type="checkbox"/> | Errata |
| Fab | y | <input type="checkbox"/> | | Process | <input type="checkbox"/> |
| Material | Materials | <input type="checkbox"/> | Packing/Shipping/Labelin | <input type="checkbox"/> | Electrical |
| s | [X] | g | | Test | spec./Tes |
| <input type="checkbox"/> | Assembl | | | Equipmen | t |
| Wafer | y | | | t | coverage |
| Fab | Location | | | | |
| Location | | | | | |

Details of this change

Transfer of wafer backside grinding and DAF lamination from ATBK to Nexperia ATGD.

In this context, the final wafer thickness after grinding is reduced from 150µm to 120µm.

CN-202302012F_SelfQualificationReport.pdf:
https://qcm.nexperia.com/Document/DOC-562430/CN-202302012F_SelfQualificationReport.pdf

Why do we implement this change?

Due to contractual situation, Nexperia has to move out from subcontractor ATBK. To safeguard supply chain, wafer backside grinding and DAF lamination process has to be released within Nexperia.

Identification of affected products

die thickness of 120µm and date code

Product availability

Production

Planned first shipment: 20 Nov 2023

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 12 Nov 2023. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

You have received this email because you are a designated contact or subscribed to Nexperia Quality Notifications. Nexperia shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

If you would like to adjust your mailing preferences, please click [here](#).